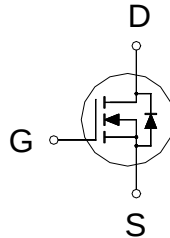


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	60V
$R_{DS(on)} (MAX.)$	60m Ω
I_D	3.5A



UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25\text{ }^{\circ}\text{C}$	I_D	3.5	A
	$T_A = 70\text{ }^{\circ}\text{C}$		2.3	
Pulsed Drain Current ¹		I_{DM}	14	
Power Dissipation	$T_A = 25\text{ }^{\circ}\text{C}$	P_D	1.25	W
	$T_A = 70\text{ }^{\circ}\text{C}$		0.83	
Operating Junction & Storage Temperature Range		T_{j}, T_{stg}	-55 to 150	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Ambient	$R_{\theta JA}$		100	$^{\circ}\text{C} / \text{W}$

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

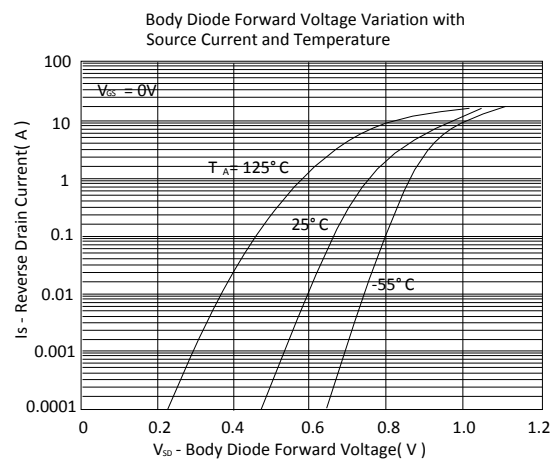
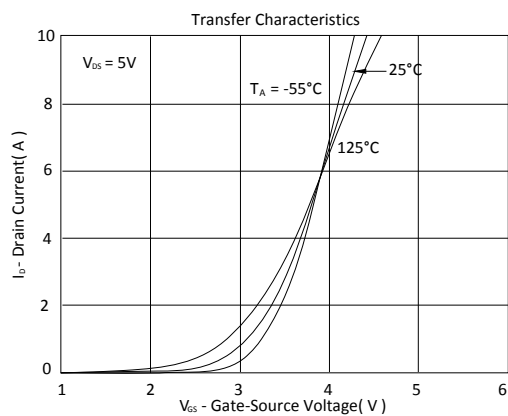
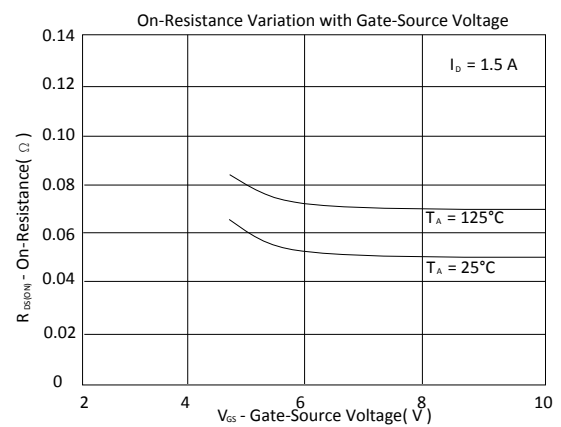
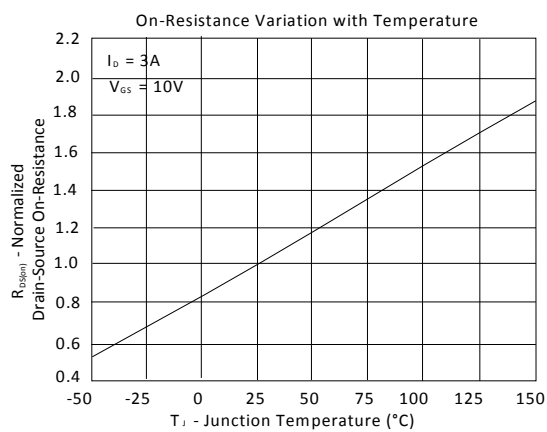
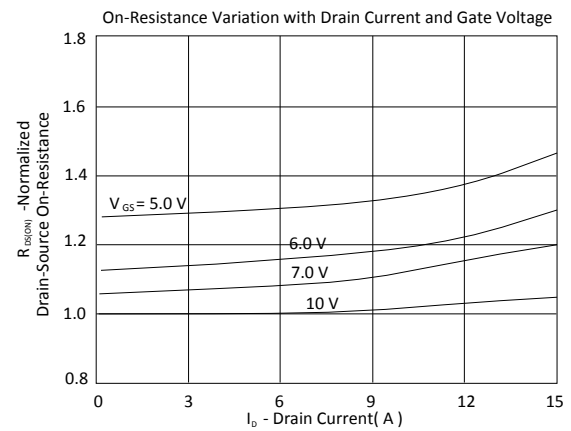
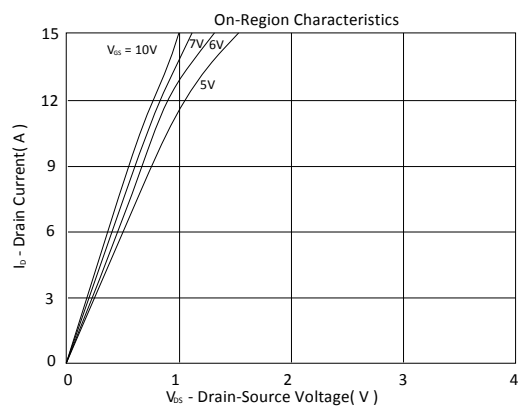
ELECTRICAL CHARACTERISTICS ($T_c = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

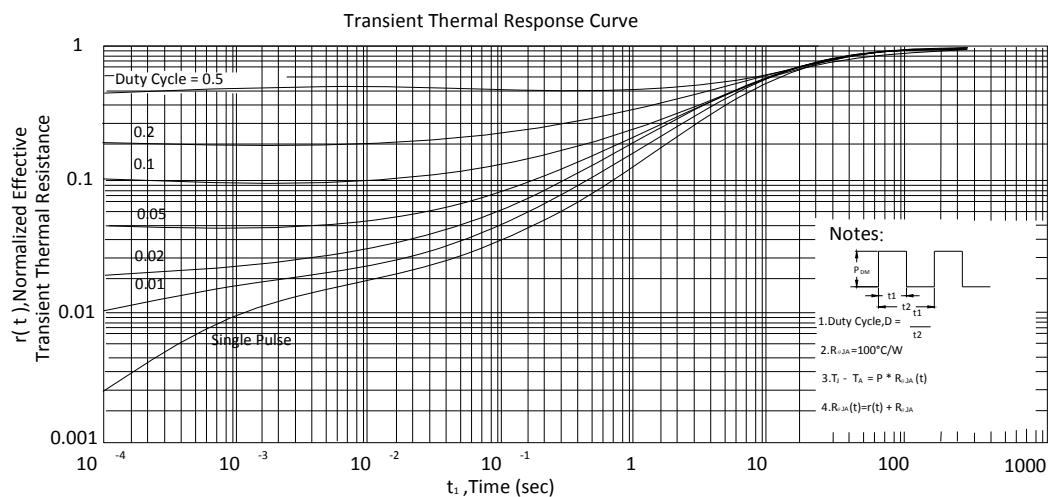
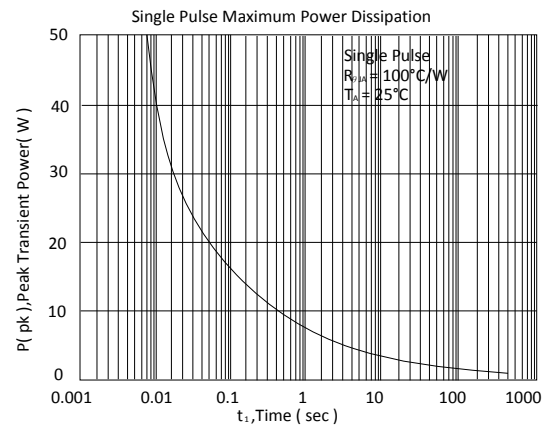
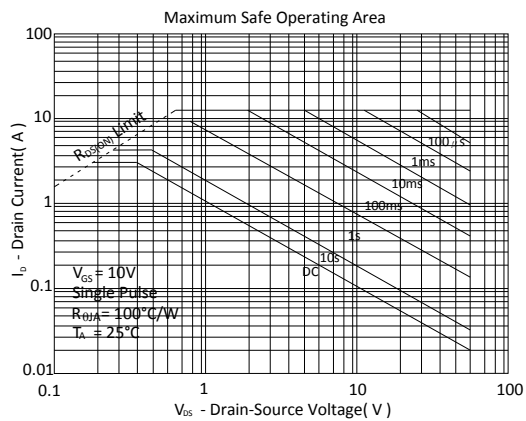
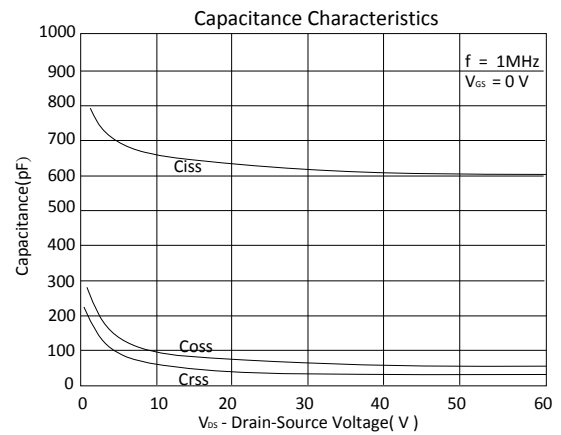
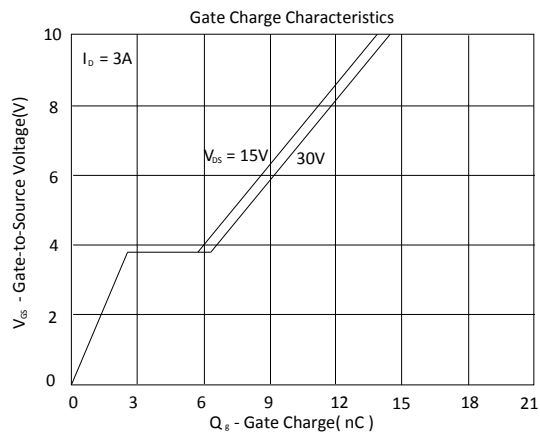
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	2.0	3.2	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 48V, V_{GS} = 0V$			1	μA
		$V_{DS} = 40V, V_{GS} = 0V, T_J = 125\text{ }^{\circ}C$			25	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = 5V, V_{GS} = 10V$	3.5			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 3A$		50	60	m Ω
		$V_{GS} = 5V, I_D = 2A$		58	75	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 3A$		12		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 30V, f = 1MHz$		633		pF
Output Capacitance	C_{oss}			67		
Reverse Transfer Capacitance	C_{rss}			44		
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = 30V, V_{GS} = 10V,$ $I_D = 3A$		13.8		nC
Gate-Source Charge ^{1,2}	Q_{gs}			2.8		
Gate-Drain Charge ^{1,2}	Q_{gd}			4.0		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = 30V,$ $I_D = 1A, V_{GS} = 10V, R_{GS} = 6\Omega$		10		nS
Rise Time ^{1,2}	t_r			12		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			20		
Fall Time ^{1,2}	t_f			15		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _c = 25 °C)						
Continuous Current	I_S				2	A
Pulsed Current ³	I_{SM}				8	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			1.2	V

¹Pulse test : Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

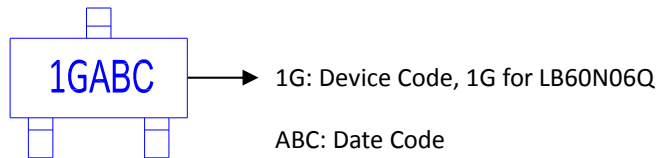
³Pulse width limited by maximum junction temperature.



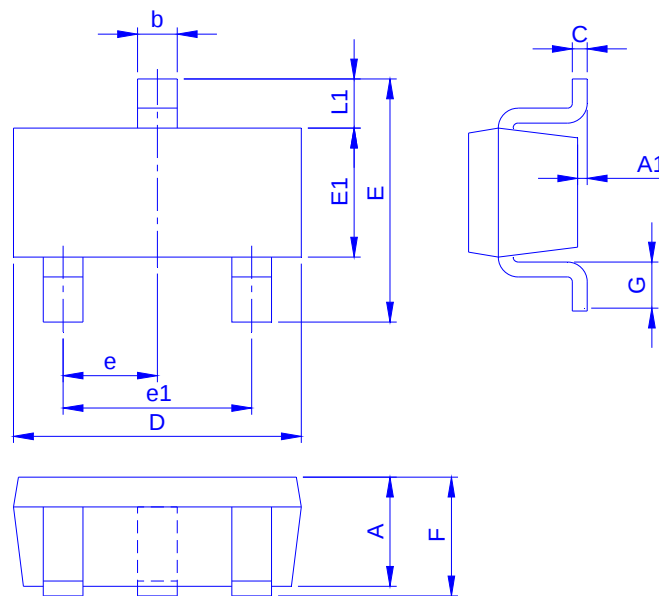


Ordering & Marking Information:

Device Name: EMB60N06J for SOT-23



Outline Drawing



Dimension in mm

Dimension	A	A1	A2	b	C	D	E	E1	e	e1	F	G	L1
Min.	0.7	0		0.35	0.1	2.8	2.6	1.5	0.9		0.8	0.3	0.55
Typ.						2.9	2.8	1.6	0.95	1.9			
Max.	1.12	0.1		0.5	0.2	3	3	1.7	1		1.2	0.6	0.65

Footprint

